This listing of claims replaces all prior versions, and listings, of claims in the present application.

Listing of Claims:

Claims 1-80 canceled.

81. (new) A method for making a carrier for a semiconductor device, said method comprising:

forming a seat with a cut out portion in at least one trace located on a substrate, said seat being sized and configured to receive a conductive connecting structure; and

providing an elastomeric material over said substrate and said at least one trace with a gap at said seat to allow electrical connection of the conductive connecting structure with a semiconductor die,

wherein said forming a seat with a cut out portion comprises extending the cut out portion to the at least one trace located on the substrate.

82. (new) The method of claim 81, further comprising the act of affixing the conductive connecting structure to said cut out portion.

83. (new) The method of claim 82, wherein said affixing comprises affixing a solder ball to said seat.

84.. (new) The method of claim 83, further comprising electroplating said seat with one or more metals.

85. (new) The method of claim 81, further comprising affixing the conductive connecting structure to said semiconductor die.

86. (new) The method of claim 81, wherein forming comprises forming a seat with a cut out portion for each trace.

87. (new) The method of claim 81, wherein said forming comprises laser drilling.

88. (new) The method of claim 81, wherein said forming comprises mechanical drilling.

89. (new) The method of claim 81, wherein said forming comprises etching.

90. (new) The method of claim 81, wherein said forming comprises mechanical coining.

91. (new) The method of claim 81, wherein said forming comprises laser ablating.

92. (new) A method for making a carrier for a semiconductor device, said method comprising:

forming a seat with a cut out portion in at least one trace located on a substrate, said seat being sized and configured to receive a conductive connecting structure; and

providing an elastomeric material over said substrate and said at least one trace with a gap at said seat to allow electrical connection of the conductive connecting structure with a semiconductor die,

wherein said forming a seat with a cut out portion comprises extending the cut out portion into the substrate.

93. (new) A method of making a semiconductor device comprising:

assembling a carrier, said assembling comprising:

forming a seat with a cut out portion in at least one trace located on a substrate, said seat being sized and configured to receive a conductive connecting structure, and

positioning an elastomeric material over said substrate and said at least one trace with a gap at said seat to allow electrical connection of the conductive connecting structure with a semiconductor die; and

electrically connecting said carrier with the semiconductor die,

wherein said forming a seat with a cut out portion comprises extending the cut out portion into the substrate.

94. (new) The method of claim 93, further comprising affixing the conductive connecting structure to said cut out portion.

95. (new) The method of claim 94, wherein said affixing comprises affixing a solder ball to said seat.

96.. (new) The method of claim 95, further comprising electroplating said seat with one or more metals.

97. (new) The method of claim 93, further comprising affixing the conductive connecting structure to said semiconductor die.

98. (new) The method of claim 93, wherein forming comprises forming a seat with a cut out portion for each trace.

99. (new) The method of claim 93, wherein said forming comprises laser drilling.

100. (new) The method of claim 93, wherein said forming comprises mechanical drilling.

101. (new) The method of claim 93, wherein said forming comprises etching.

102. (new) The method of claim 93, wherein said forming comprises mechanical coining.

103. (new) The method of claim 93, wherein said forming comprises laser ablating.

104. (new) A method of making a semiconductor device comprising:

assembling a carrier, said assembling comprising:

forming a seat with a cut out portion in at least one trace located on a substrate, said seat being sized and configured to receive a conductive connecting structure, and

positioning an elastomeric material over said substrate and said at least one trace with a gap at said seat to allow electrical connection of the conductive connecting structure with a semiconductor die; and

electrically connecting said carrier with the semiconductor die,

wherein said forming a seat with a cut out portion comprises extending the cut out portion to the at least one trace located on the substrate.